



景碩科技股份有限公司
Kinsus Interconnect Technology Corp.

Aug 2024



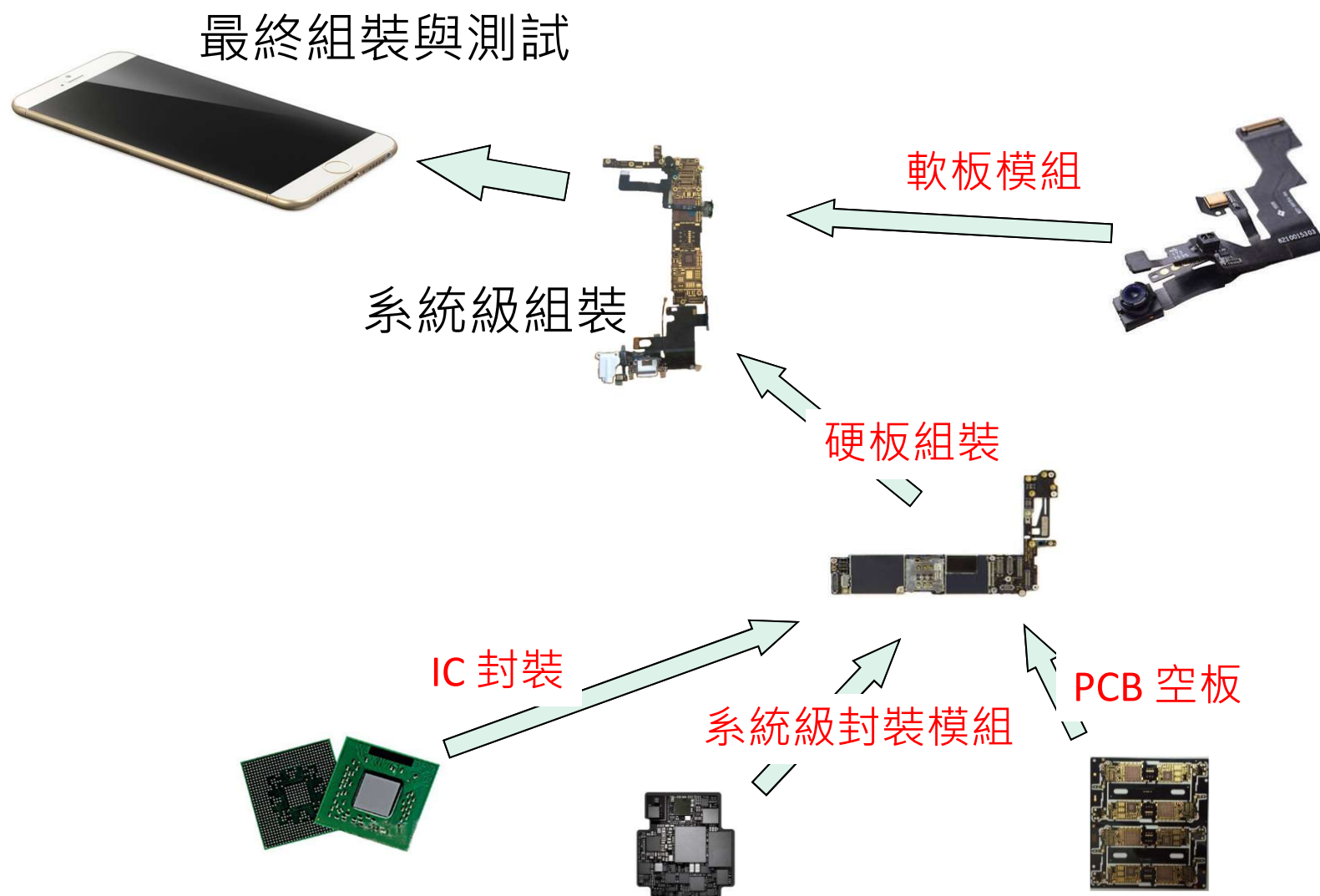


IC 封裝技術

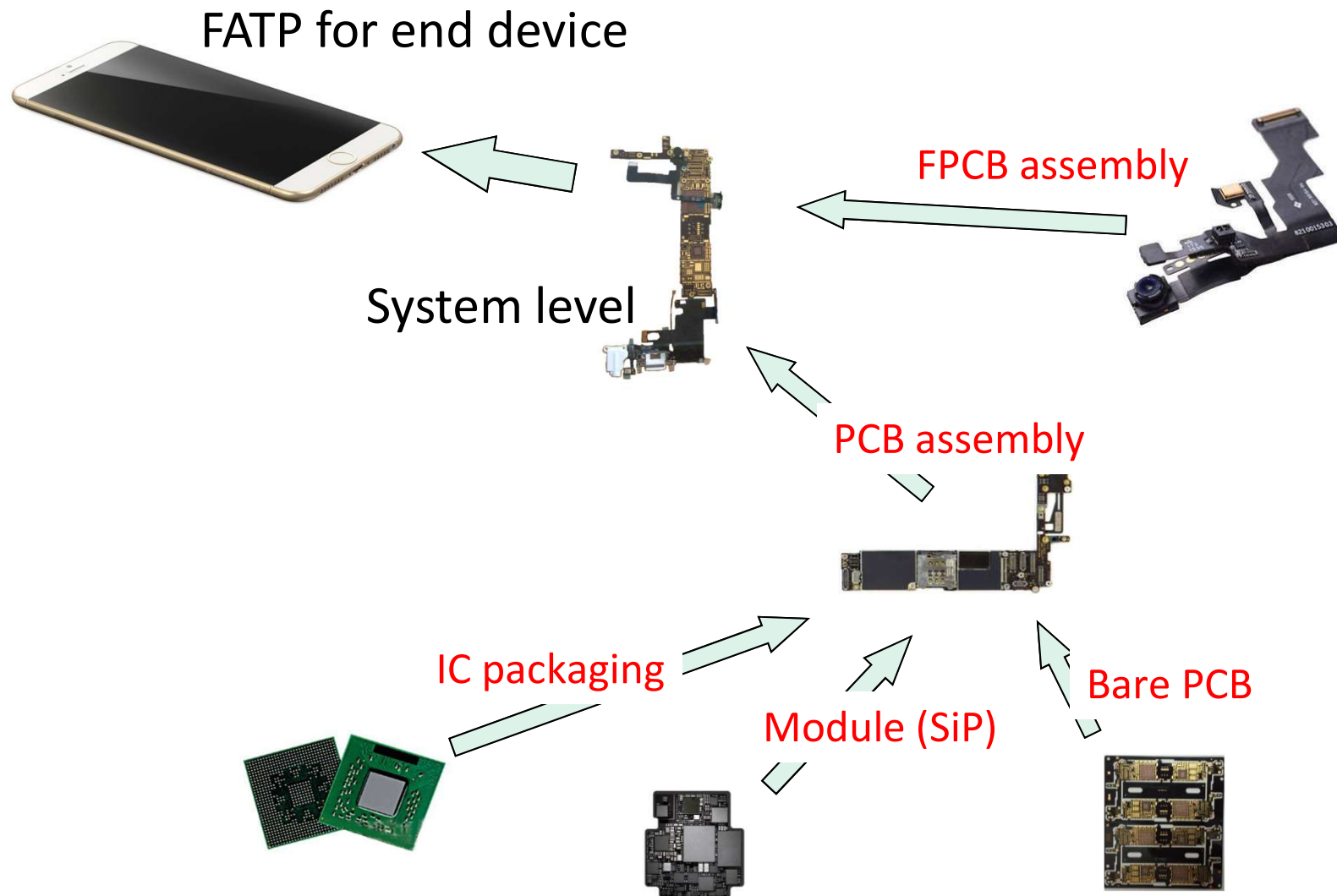
IC Packaging Technology



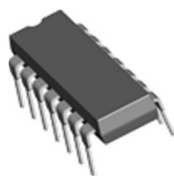
電子產品構裝的各個層次



Levels of Assembly



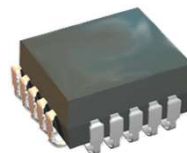
各種形式的IC 封裝



DIP



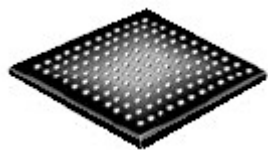
QFP



PLCC



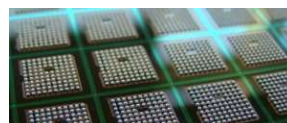
TSOP



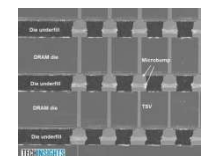
PBGA/
Flip-Chip BGA



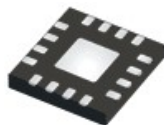
CSP



WLP



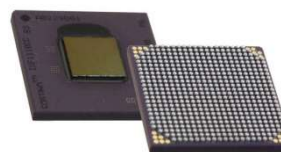
TSV



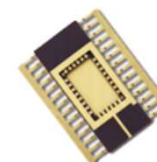
QFN



DFN



Ceramic BGA

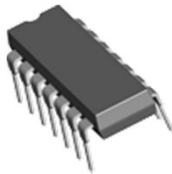


Ceramic chip

BGA 封裝 市場規模: 2023 年828 億顆, 產值 161億美元



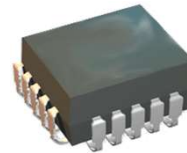
Different types of IC packaging



DIP



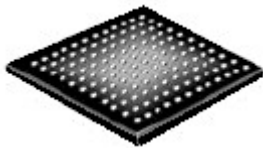
QFP



PLCC



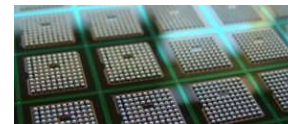
TSOP



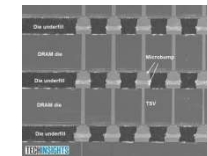
PBGA/
Flip-Chip BGA



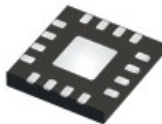
CSP



WLP



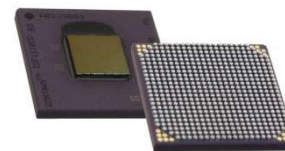
TSV



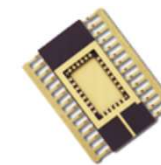
QFN



DFN



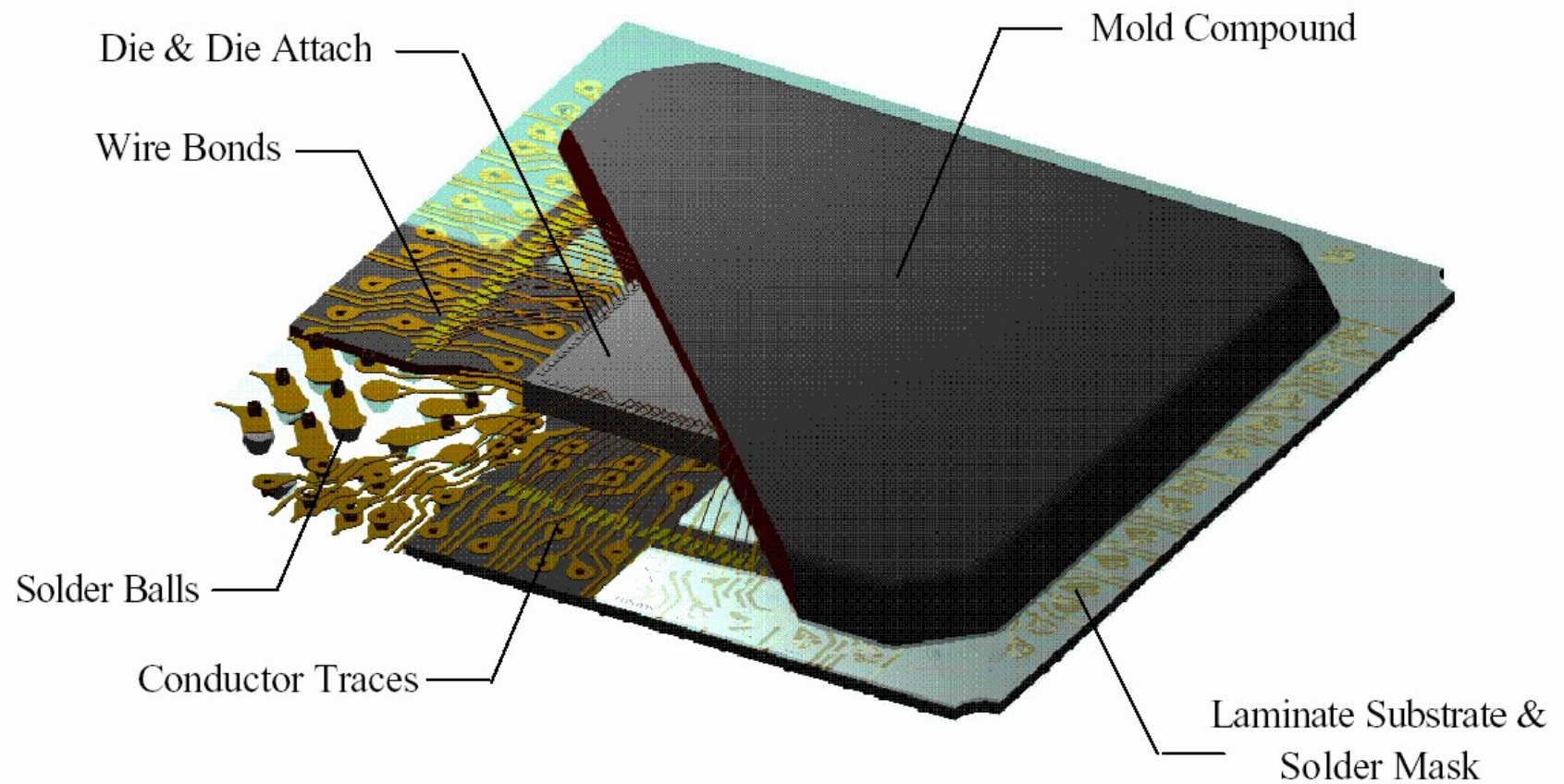
Ceramic BGA



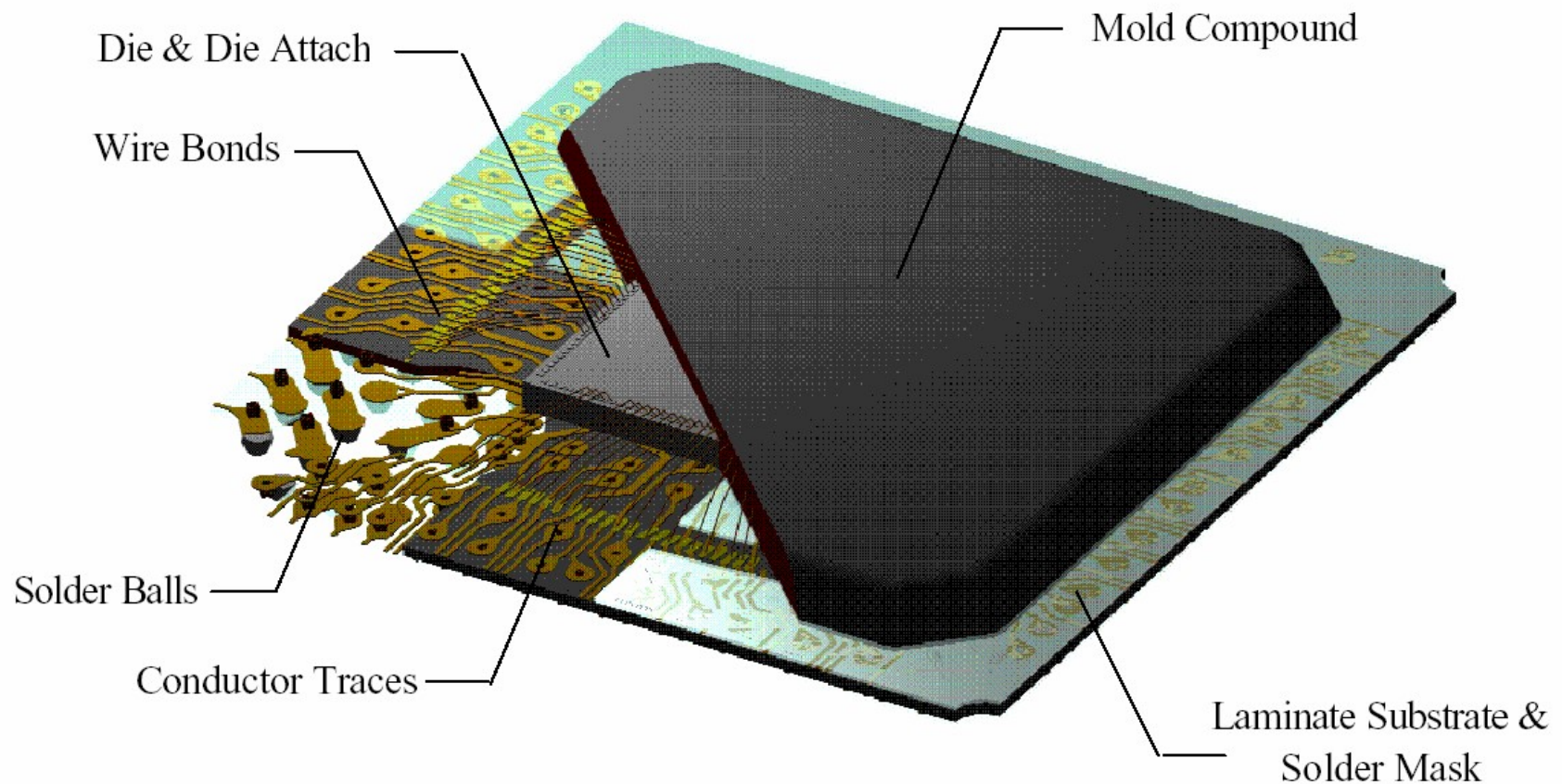
Ceramic chip

BGA Market size : 82 Billion units, 16 Billion US\$ in 2023

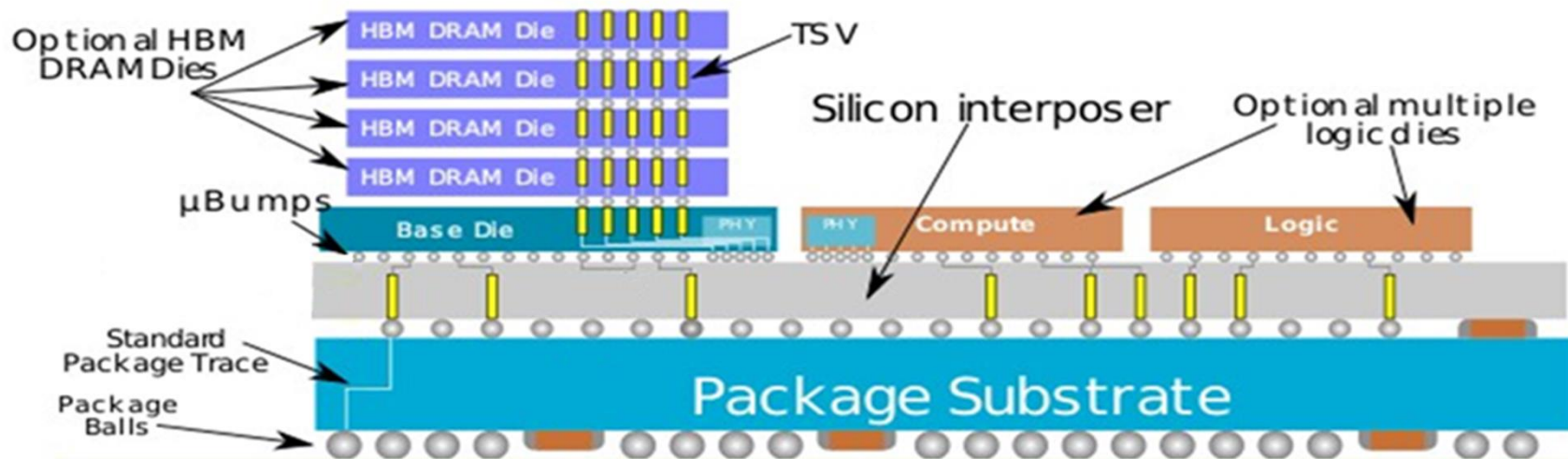




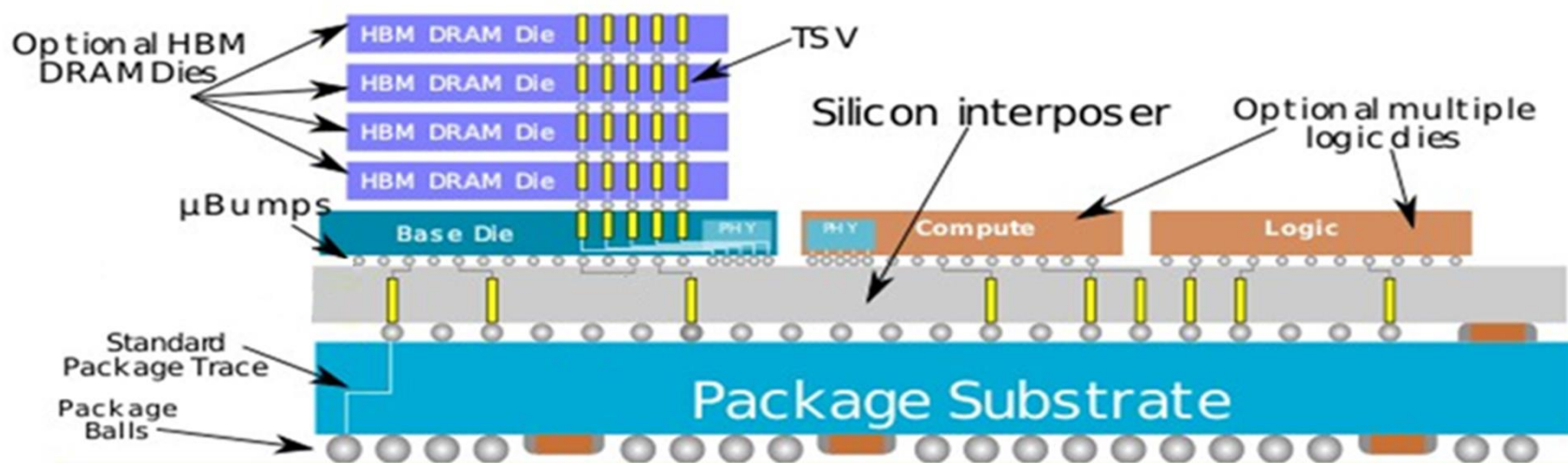
What Substrate Makers do?



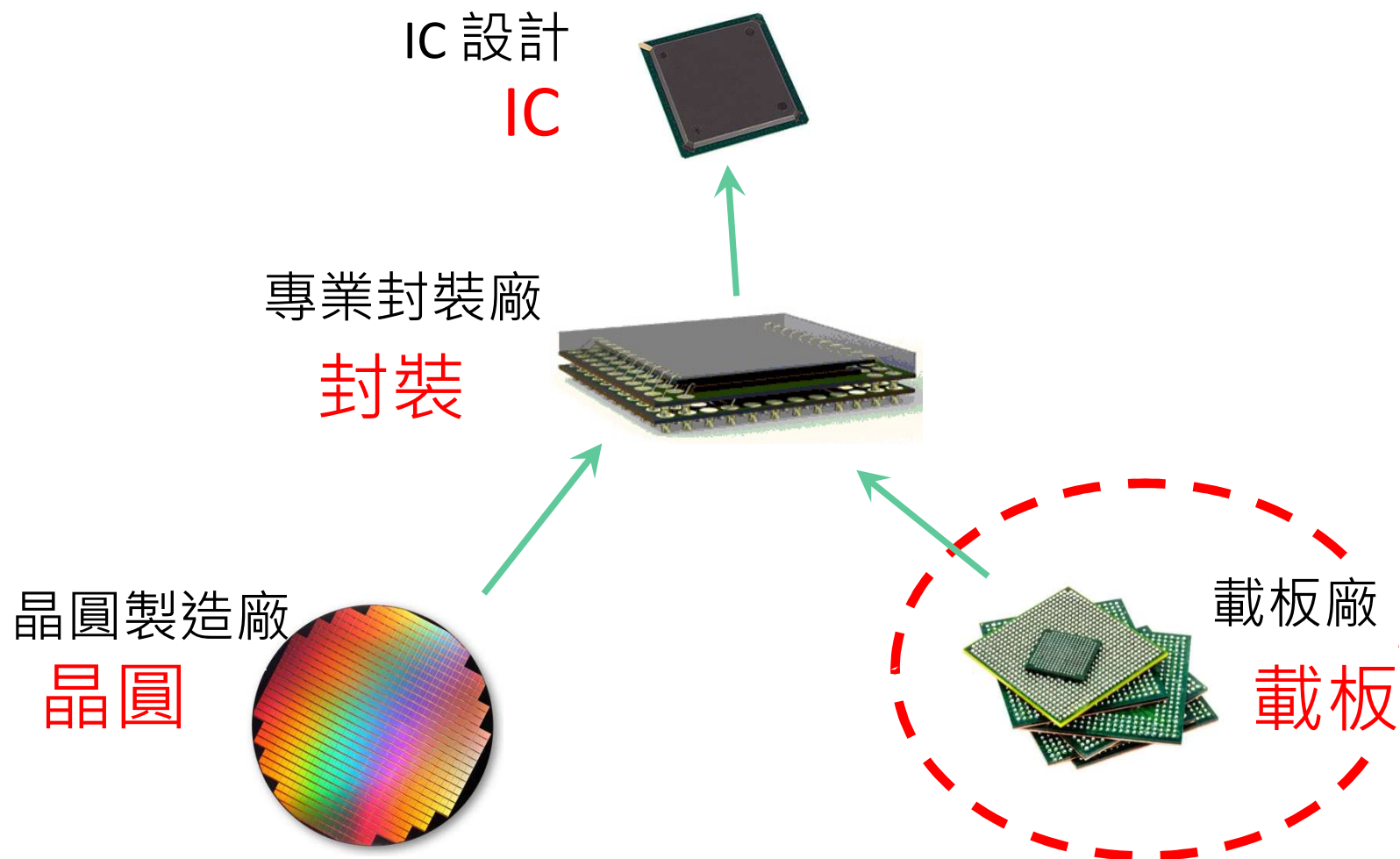
CoWoS



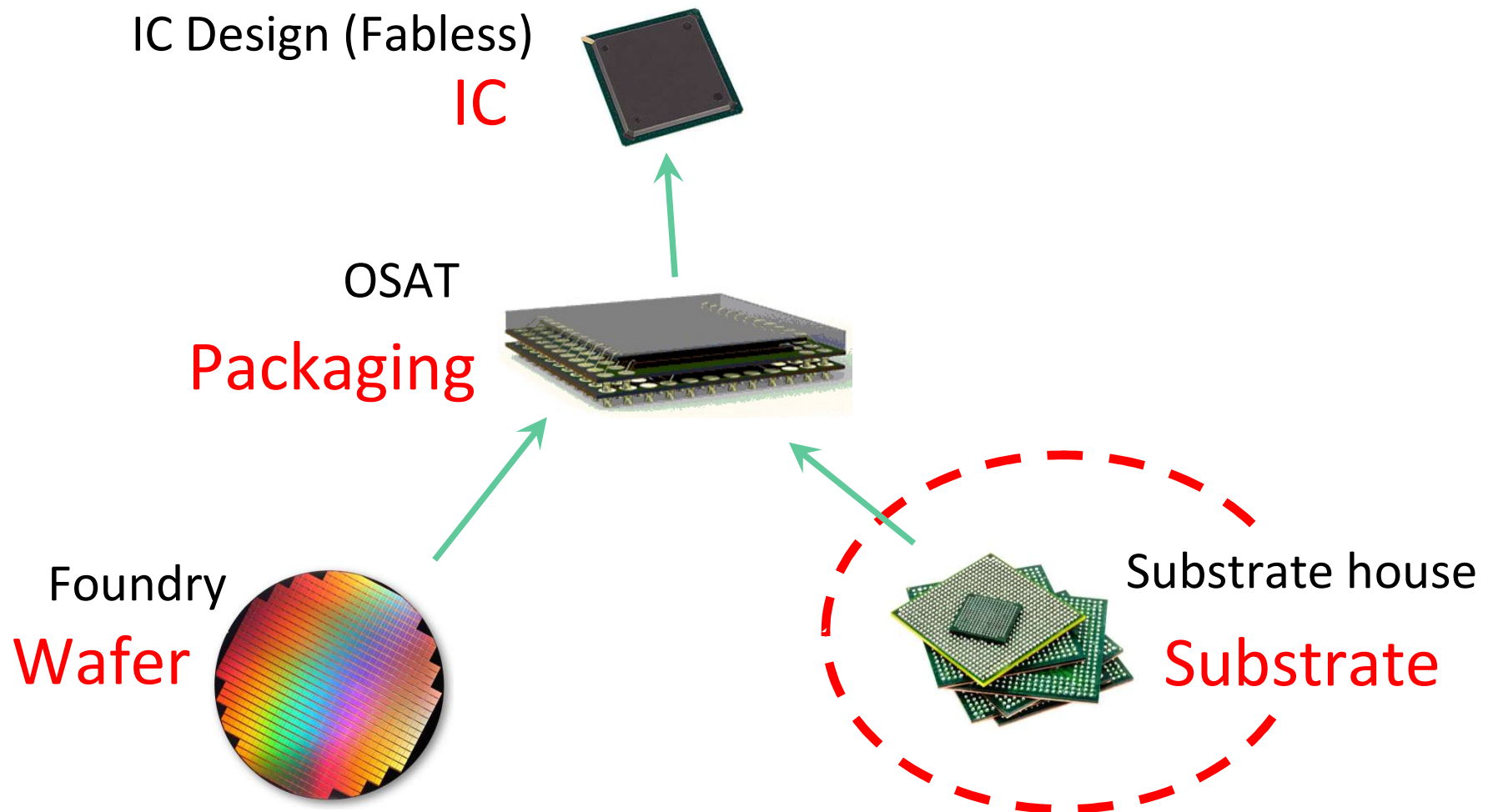
CoWoS



IC 半導體上下游供應鏈關係



IC Manufacturing Supply Chain





About Kinsus



基本資料



- 公司成立 2000
台股上市掛牌 2004
- 資本額： 新台幣 45.45 億元
- 廠區： 總部
 IC 載板

 Kinsus USA
 統碩科技
 晶碩光學
- 新屋 / 台灣
- 一廠 及 二廠
- 五廠 及 六廠
- Santa Clara / California
- 蘇州 / 中國
- 桃園 / 台灣



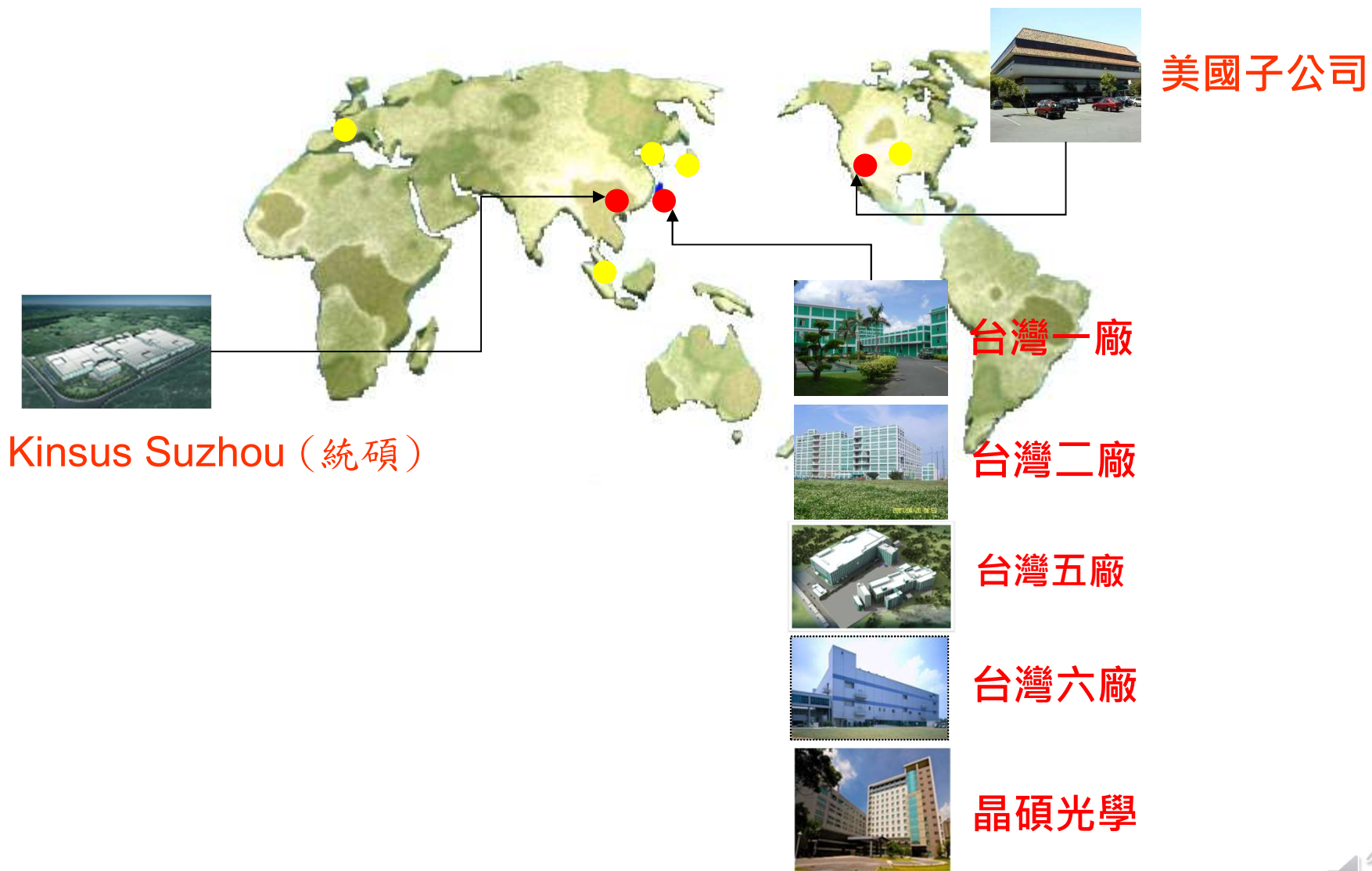
Basic Information



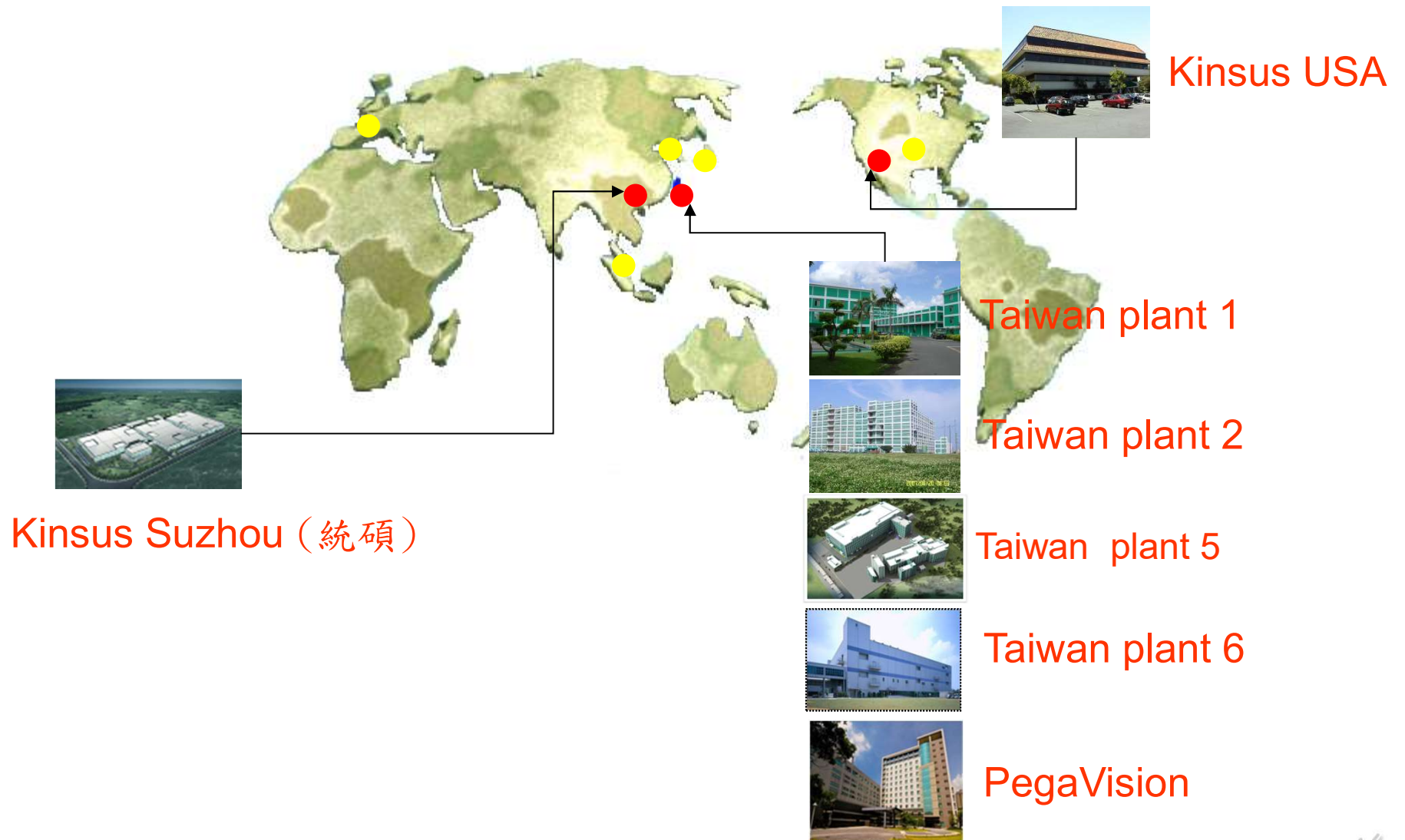
- Established in September 2000
IPO at TWSE in November 2004
- Capital : US\$ 147 Million (NT\$ 4.545 Billion)
- Campus :
 - Headquarters
 - Xin Wu / Taiwan
 - Plant 1 & 2
 - Plant 5 & 6
 - IC substrates
 - Kinsus USA
 - Santa Clara / California
 - Kinsus China
 - Suzhou / China
 - PegaVision
 - Taoyuan / Taiwan



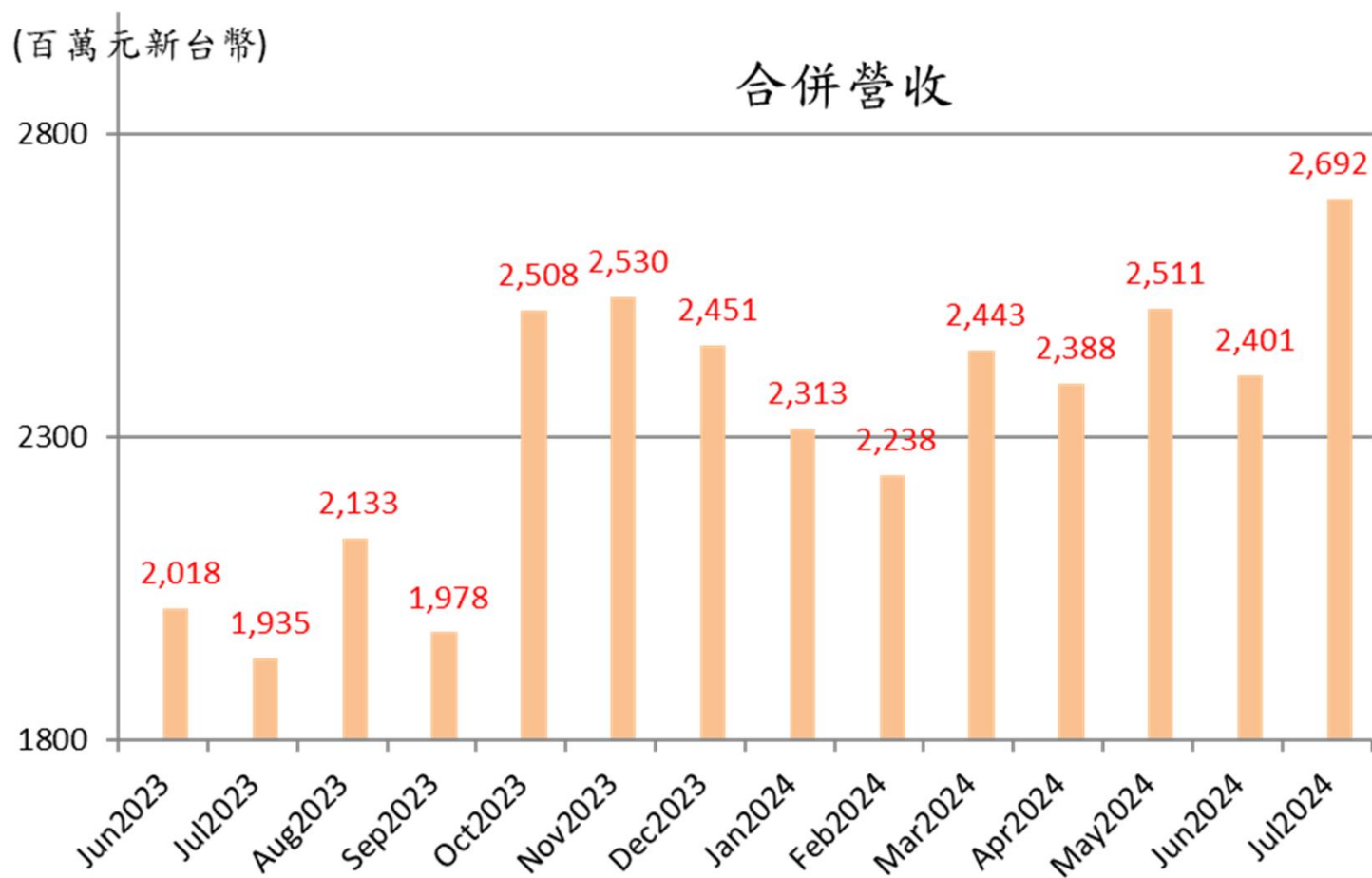
位置



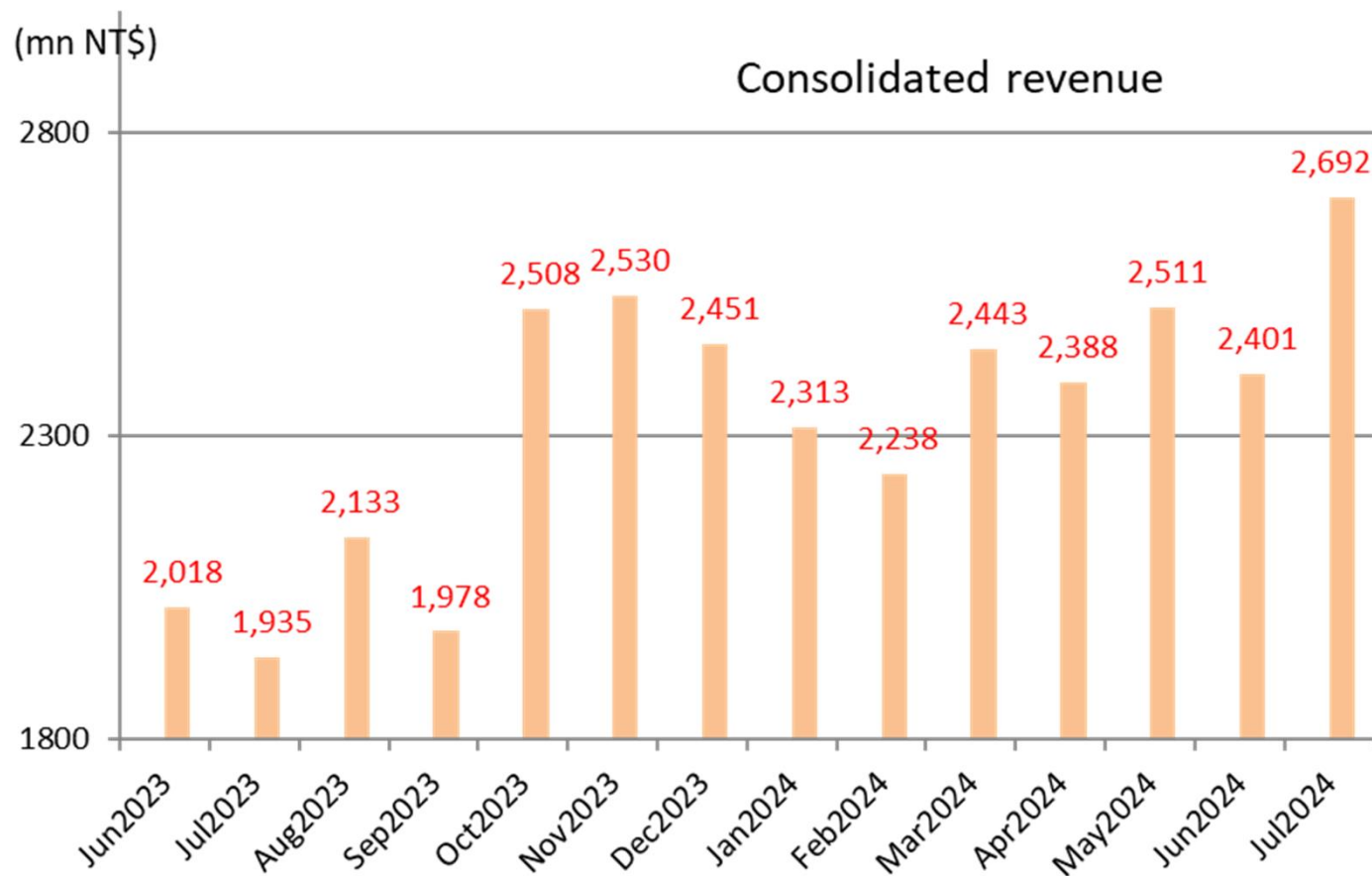
Locations



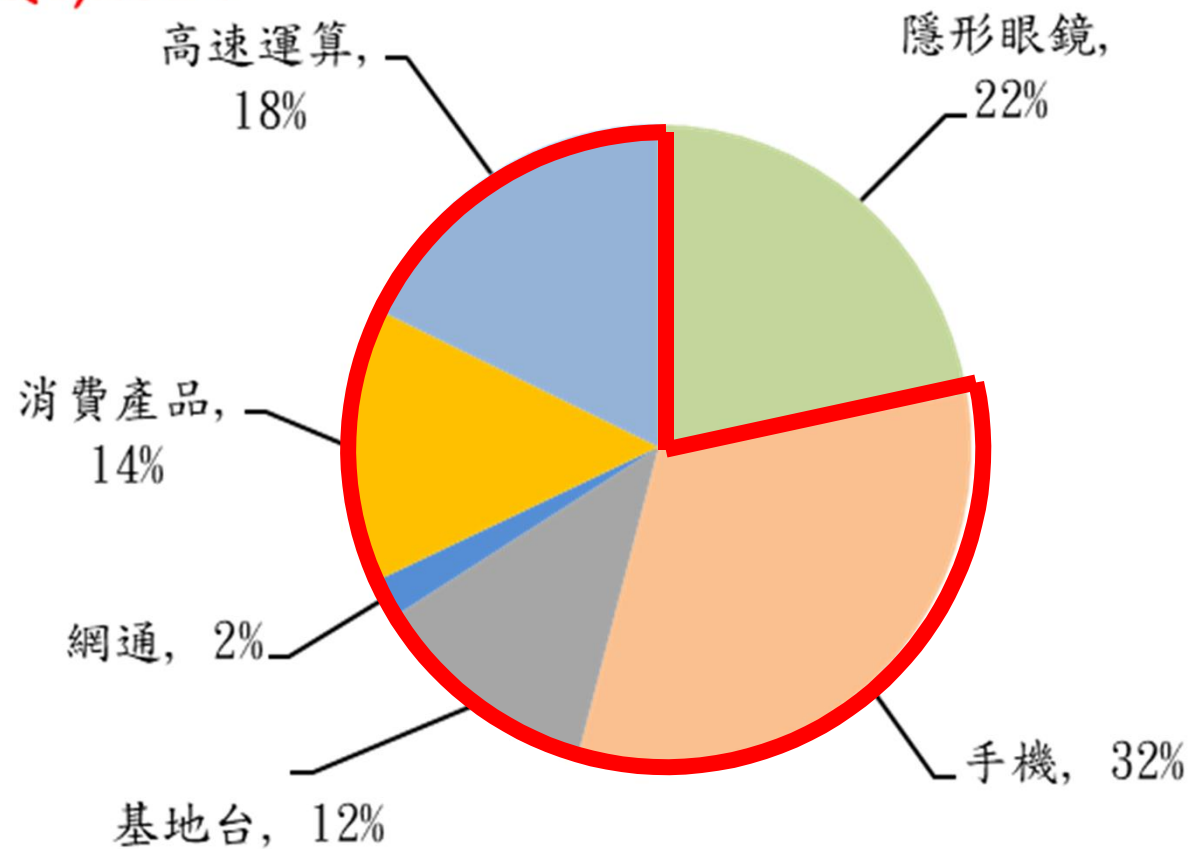
每月營業額



Monthly Revenue



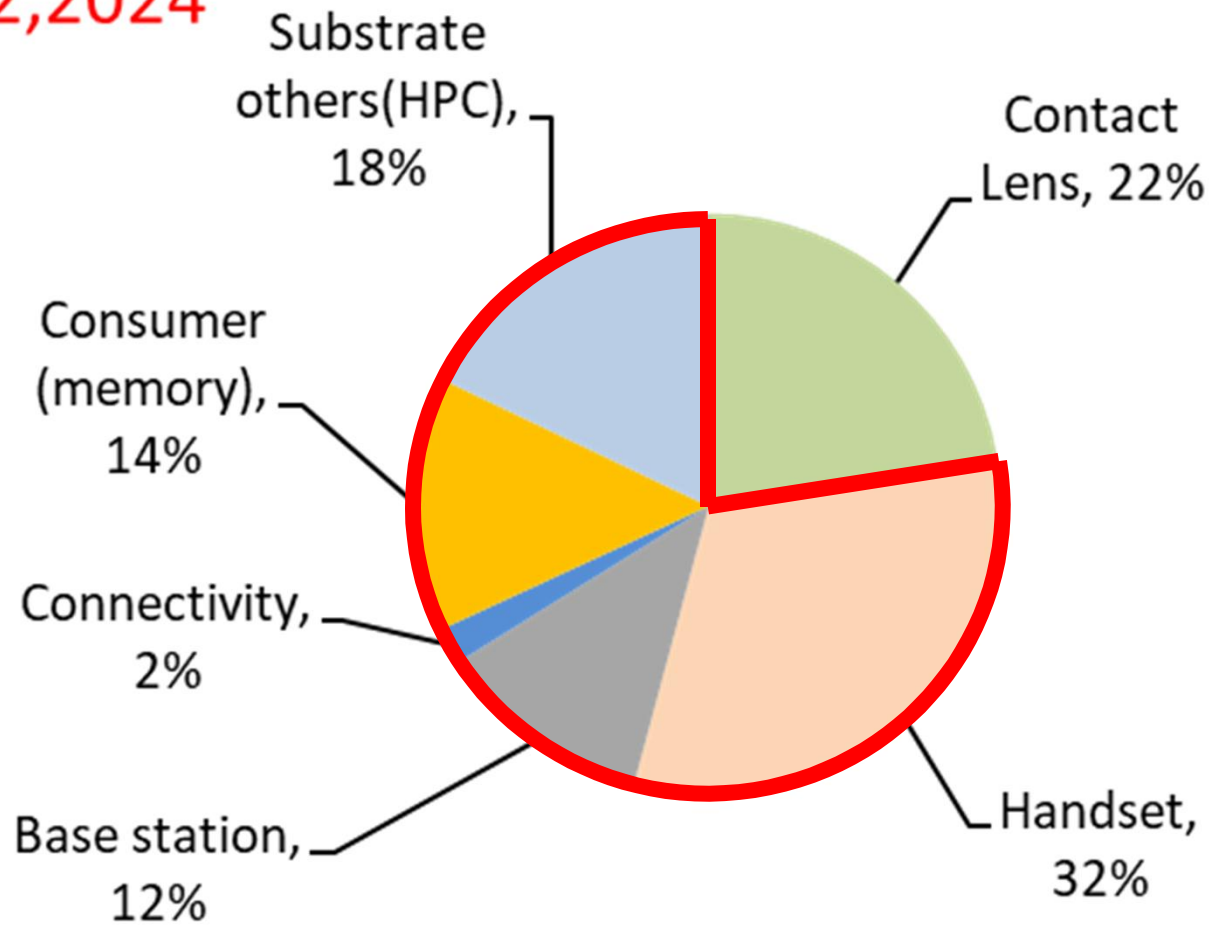
Q2, 2024



Product mix



Q2,2024





Thank you

